

BZT52BXXX

Rev.H Jan.-2024

5 é / Descriptions

SOD-123 .> // x l 9 8 â 'ož

Zener Diode in a SOD-123 Plastic Package.

□^a / Features

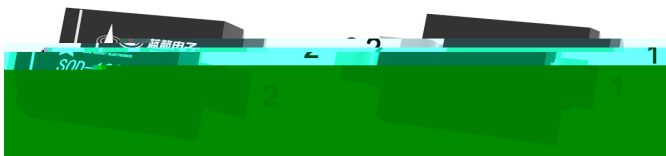
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500mW power dissipation, medium current, automated assembly processes, HF Product.

Đ ÷ / Applications

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2.4V to 39V wide zener voltage range applications.



PIN1:Cathode

PIN2:Anode

, M V / Marking

• - ~^a ¢ož

See Marking Instructions.

@ f Parameter	... Z Symbol	f > Rating	% y Unit
Forward Voltage (Note 2) I _F =10mA	V _F	0.9	V
Power Dissipation(Note 1)	P _D	500	mW
Typical Thermal Resistance Junction to Ambient(Note 1)	R _{JA}	305	/W
Junction and Storage Temperature Range	T _j , T _{stg}	-65 150	

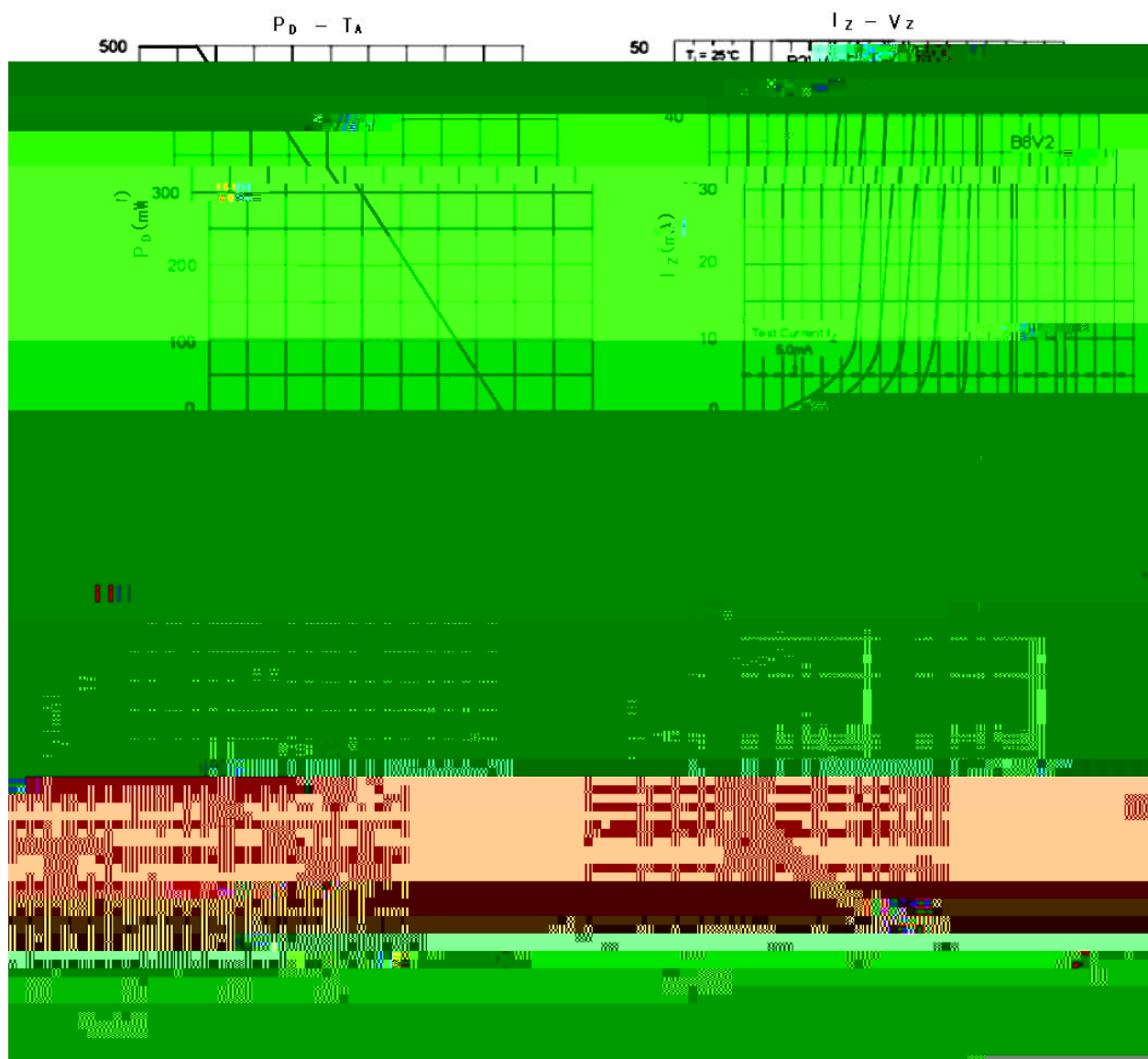
Type Number	Mark- ing Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		V _z @I _{ZT}			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _{ZK}	I _R	@V _R
		Nom (V)	Min (V)	Max (V)	mA				A	V

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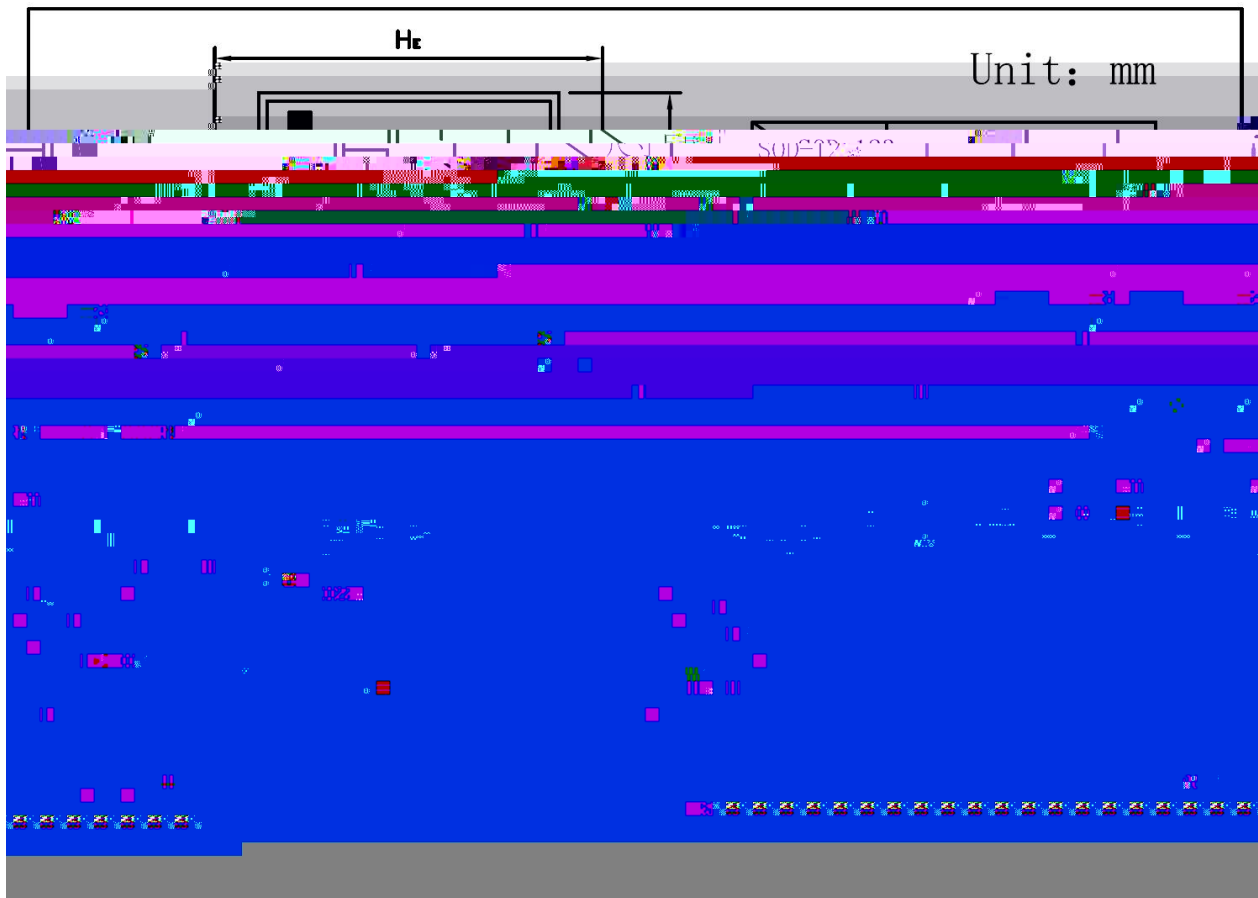
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm².
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

Electrical Characteristic Curve



Ø □ =) ☎ / Package Dimensions



BZT52BXXX

šWD t...•Ž¢ (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

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- 1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;
- 2o• Q > “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;
- 3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

- 1.Preheating:150~180 - , Time:60~90sec.
- 2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
- 3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec. Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ~ E	Units ;>û !H	Dimension ;>û p . (unit Åmm³)
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